

INTERNATIONAL STANDARD

**Packaging of components for automatic handling –
Part 5: Matrix trays**





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**Packaging of components for automatic handling –
Part 5: Matrix trays**

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms, definitions and abbreviated terms	7
3.1 Terms and definitions.....	7
3.2 Abbreviated terms.....	7
4 Material	8
4.1 Electrostatic dissipative requirements	8
4.2 Effect of properties	8
4.3 Recycling and rigidity.....	8
5 Mechanical stability	8
5.1 Loaded tray.....	8
5.2 Empty tray	8
5.3 Outer edges.....	8
6 Tray design, dimensions and other physical properties	8
6.1 Tray design.....	8
6.1.1 Number of pockets.....	8
6.1.2 Orientation of pockets.....	8
6.1.3 Design rules for pocket density.....	9
6.2 Overall tray dimensions	10
6.3 Cell dimensions	10
6.4 Tray vacuum pick-up sites	11
6.4.1 Size	11
6.4.2 Centre	11
6.4.3 Perimeter.....	11
6.5 Detail features	11
6.6 Weight	12
6.7 Movement of components	12
6.8 Dimensional information.....	12
7 Polarity and orientation of components in the tray	15
7.1 Pin one	15
7.2 Loading.....	15
8 Tray stacking.....	15
8.1 Bundling	15
8.2 Top protection.....	16
8.3 Partial filling.....	16
8.4 Protrusion of components	16
8.5 Stack-up	16
8.6 Damaging of components.....	16
8.7 Warpage	16
9 Missing components	16
10 Marking	16
Annex A (informative) List of existing matrix trays with wide anticipated use in the electronic industries	17
A.1 Matrix trays (for different packages).....	17

A.2	Matrix trays for PGA packages.....	25
A.2.1	Dimensional information	25
A.2.2	Variation sheet PGA (pin grid array package)	28
Annex B	(normative) Measurement methodology of the tray dimensions	29
B.1	General.....	29
B.2	Definition of the dimensions	29
B.2.1	Outline dimensions	29
B.2.2	Tray thickness (<i>A</i>).....	30
B.2.3	Dimensions of the stacking feature	31
B.2.4	Warpage.....	31
B.3	Measuring instrument.....	31
B.4	Measurement conditions	31
B.5	Measurement methodology	31
B.5.1	Outline dimensions	31
B.5.2	Tray thickness (<i>A</i>).....	32
B.5.3	Dimensions of the stacking feature	33
B.5.4	Warpage.....	33
Annex C	(normative) Matrix trays – General considerations for design (design value).....	34
C.1	Lateral movement of leaded devices	34
C.2	Lateral movement of un-leaded devices	34
C.3	Lead protection.....	35
Figure 1	– Sample of leaded packages	11
Figure 2	– Sample of grid array packages	11
Figure 3	– Tray main view.....	13
Figure 4	– Tray stacking details	14
Figure 5	– Tray tolerances	14
Figure A.1	– Thin tray	18
Figure A.2	– Thick matrix	26
Figure B.1	– Cross-sections of the outline dimensions	30
Figure B.2	– Tray thickness	30
Figure B.3	– Examples of tray warpage.....	31
Figure B.4	– Top view of a tray showing the measurement locations for the outline dimensions	32
Figure B.5	– Measurement locations for tray thickness	32
Figure B.6	– Holding position in calliper jaws for measurement.....	32
Figure B.7	– Correction of a lift of the tray at the measurement point.....	32
Figure B.8	– Measurement locations for the stackable design	33
Figure B.9	– Measurement points for warpage	33
Figure C.1	– Lateral movement of leaded devices A to I	34
Figure C.2	– Lateral movement of un-leaded devices check points A to C.....	34
Figure C.3	– Lateral movement of un-leaded devices check points D to F.....	35
Figure C.4	– Lead protection gap.....	35
Table 1	– <i>P</i> and <i>W</i> dimension.....	9
Table 2	– Height dimensions.....	10

Table 3 – Notes related to Figures 3 and 4	15
Table A.1 – Variations	19
Table A.2 – Notes related to Figures A.1 and A.2.....	27
Table A.3 – PGA variations	28

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 5: Matrix trays**

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International Standard IEC 60286-5 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 2003 and Amendment 1:2009. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) The generic rules for the design of matrix trays are given in this document. Newly developed trays which follow these rules will not be listed individually. Only those trays which conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.
- b) An update of the matrix trays, which do not conform to the design rules set forth herein, are considered as "non-standard trays" and are not preferred for use, is listed in Annex A.

The text of this International Standard is based on the following documents:

CDV	Report on voting
40/2556/CDV	40/2597/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60286 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 5: Matrix trays

1 Scope

This part of IEC 60286 describes the common dimensions, tolerances and characteristics of the tray. It includes only those dimensions that are essential for the handling of the trays for the stated purpose and for placing or removing components from the trays.

Matrix trays are designed to facilitate the transport and handling of electronic components during their testing, baking, transport/storage, and final mounting by automatic placement equipment.

The generic rules for their design are given in this document. Newly developed trays that follow these rules will not be listed individually. Only those trays that conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.

NOTE Matrix trays listed in Annex A that do not conform to the design rules set forth herein shall be considered as "non-standard trays" and are not preferred for use.

2 Normative references

There are no normative references in this document.

3 Terms, definitions and abbreviated terms

3.1 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.2 Abbreviated terms

The following are the abbreviated terms used in Table A.1 and Table A.3.

ball grid array (ball grid array type package)	BGA
ceramic quad flat package (ceramic quad flat type package)	CQFP
metric quad flat package (metric quad flat type package)	MQFP
plastic leaded chip carrier (plastic leaded type chip carrier)	PLCC
plastic quad flat package (plastic quad flat type package)	PQFP
thin quad flat package (thin quad flat type package)	TQFP
small outline j-leaded package (small outline j-leaded type package)	SOJ
type 1 thin small outline package (thin small outline type package1)	TSOP (I)
type 2 thin small outline package (thin small outline type package2)	TSOP (II)